

**ABSTRACT**

**Method for the thin interconnection of active and passive components and resulting thin heterogeneous component**

The present invention relates to a method for the thin interconnection of active and passive components in two or three dimensions, and to the resulting thin heterogeneous components.

According to the invention, the method comprises:

- positioning and fixing (11) at least one active component and one passive component on a flat support (23), the terminals being in contact with the support,
- depositing (12) a polymer layer (24) on all of the support and said components,
- removing the support (14),
- redistributing the terminals (15) between the components and/or toward the periphery by means of metal conductors (26) arranged in a predetermined layout, making it possible to obtain a heterogeneous reconstituted structure,
- heterogeneously thinning (16) said structure by nonselective surface treatment of the polymer layer and at least one passive component (22).

Fig. 2B